HIGH-SPEED GROUND PLANE HEADER

SPECIFICATIONS
For complete specifications and recommended PCB layouts see www.samtec.com/QTE

Insulator Material:
Liquid Crystal Polymer

Terminal Material:
Phosphor Bronze

Plating:
Au or Sn over 50 μ" (1.27 μm) Ni

Current Rating:
Contact:
2 A per pin
(2 pins powered)
Ground Plane:
23 A per ground plane
(1 ground plane powered)

Operating Temp Range:
-55 °C to +125 °C

Voltage Rating:
225 VAC mated with QSE & 5 mm Stack Height

Max Cycles:
100

RoHS Compliant:
Yes

PROCESSING
Lead–Free Solderable:
Yes

SMT Lead Coplanarity:
(0.10 mm) .004" max (020-060)

Board Stacking:
For applications requiring more than two connectors per board contact igp@samtec.com

RECOGNITIONS
For complete scope of recognitions see www.samtec.com/quality

ALSO AVAILABLE
(Quantity Required)
• 15 mm, 22 mm and 30 mm stack height
• 50 μ" (0.76 μm) Gold
(Specify -H plating for Data Rate cable mating applications.)
• Edge Mount, Guide Posts, Screw Down & Friction Lock
• 56 (-DP), 80, 100 positions per row
• Retention Option

Note:
Some lengths, styles and options are non-standard, non-returnable.

Due to technical progress, all designs, specifications and components are subject to change without notice.

Customer specific requirements must be approved by Samtec and identified in a Samtec customer-specific drawing to apply.

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